

# NY32W

## Flexible Test and Scan Solution for FFC Devices



Automotive



Mobility



IoT/IoV & Optoelectronics



Computing & Network



Industrial & Medical



Consumer

### Productivity

- Up to 30,000 UPH
- Complete Finishing Solution
  - Full Vision inspection
  - Test Contacting
  - KGD Automotive bare die testing
- Full Device Traceability

### Flexibility

- Up to 12" Wafer Input
- 180° Flip-Chip under Turret
- 6 Sides inspection
- Tape and Reel Output
- Wide applicable device range 0.3 x 0.6 mm to 12 x 12 mm
  - Bare Die, Bumped Die
  - QFN/DFN
  - LED
  - MEMS

- 32-position Turret Test and Scan
- Down to 70 μm thin die handling
- KGD Automotive bare die testing

- Comprehensive Cohu NV-Core Inspection System
  - 3D Flex® for True Ball/Bump co-planarity
  - Full 6 Sides inspection

# NY32W

## Flexible Test and Scan Solution for FFC Devices

### Specifications

#### Platform

##### Wafer Input Media

- Film frame carrier: 4" to 12"
- Round and rectangular / plastic and metal frame
- Wafer cassette: 25 x 8", 13 x 12"

##### Device Range

- WLP: 0.3 x 0.6 to 12 x 12 mm / thickness  $\geq 0.07$  mm
- QFN: 0.3 x 0.6 to 12 x 12 mm / thickness  $\geq 0.30$  mm
- LED: 0.5 x 0.5 to 6 x 6 mm / thickness  $\geq 0.10$  mm

##### Index Time

- Down to 80 ms, depending on device and process

##### Performance Characteristics

- WLP: up to 24,000 UPH
- QFN: up to 30,000 UPH
- LED: up to 30,000 UPH
- With Wafer output: up to 20,000 UPH
- MTBA: typ. >2 h
- MTBF: typ. >168 h
- Conversion time: typ. <45 min

##### Interface

- TTL parallel interface for Tester and Laser
- RS232, GPIB (optional)
- Network: Ethernet capability
- Wafer Mapping: SECS GEM
- (SEMI E4, 5, 30, 37 SEMIG84)

##### ESD

- According to ANSI / ESD SP10.1
- ESD Class 0 (optional)

##### Facility Requirements

- 100 VAC - 240 VAC 50/60 Hz, One Phase
- 2 kVA / 3.5 kVA with vacuum pump (optional)
- Air Pressure range: 5-10 bar  $\pm 0.5$  bar
- Air consumption: 5 m<sup>3</sup>/hour (typical)
- Vacuum Network: -0.5 Bars  $\pm 10\%$
- Consumption: typ. 420 l/min (typical)

##### Dimensions

- Overall dimension: 2.3 x 2.0 x 2.1 m
- Floor space requirement: 3.0 x 2.3 x 2.1 m
- Weight: net typ. 1200 kg / gross typ. 1700 kg

- With Wafer output configuration:
  - Overall dimension: 2.8 x 1.2 x 2.1 m
  - Floor space requirement: 3.5 x 1.5 x 2.1 m
  - Weight: net typ. 1500 kg / gross yp. 2000 kg

##### Standards

- CE
- S2/S8 assessment
- 2006/42/EC Machinery
- 2004/108/EC Electromagnetic compatibility (EMC)
- 2006/95/EC Low Voltage

### Process Capabilities

#### Input

- Wafer, De-taping, Bowl, Tube

#### Output

- Tape & Reel, Tube, Tray
- Wafer output, LED 64 Bulk Sorting

#### Processes

- Device Flip
- X-Y-T touchless precisor
- Test Contacting
- Electrical Tester (Discrete)
- LED optical test (ambient & temperature 85°C)
- Laser marking
- 6 Sides Vision inspection
- Bulk, Tube, Tray Sorting
- Waffle PAK, Wafer Sorting
- Dual Tape & Reel with flip-flop
- Automatic rejection & replacement in-tape
- Auto Reel Changer
- Wafer map with full device traceability

#### NV-Core Inspection System

- 1D/2DMC code reader, ViewMap®
- 2D/3D Flex® ball/bump co-planarity
- Mark, Surface, 5S, Color Vision
- In-Tape, Post Sealing inspection
- LED dedicated solutions

#### Contactors

- Cohu offers contact sockets for all package versions and applications, i.e. One Touch Socket "High Amps", Flat Test Kelvin, Small Device Kelvin, Pogo pin pocket, LED dedicated solutions

Specifications subject to change without notice.  
For detailed performance specifications, please contact Cohu.